

ABSTRACT OF THE DISCLOSURE

5 A system for inspecting specimens such as semiconductor  
wafer is provided. The system provides scanning of dual-  
sided specimens using a damping arrangement which filters  
unwanted acoustic and seismic vibration, including an optics  
arrangement which scans a first portion of the specimen and a  
translation or rotation arrangement for translating or  
rotating the specimen to a position where the optics  
arrangement can scan the remaining portion(s) of the specimen.  
10 The system further includes means for stitching the scans  
together, thereby providing both damping of the specimen and  
the need for smaller and less expensive optical elements.